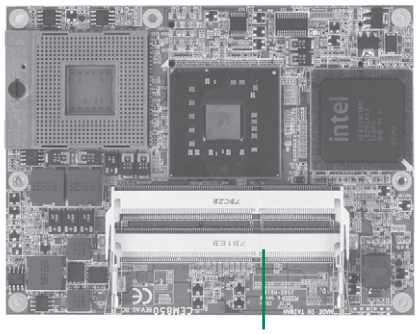
CEM850

Socket P Intel® Core™2 Duo COM Express™ Type 2 Module with Intel® GM45 + ICH9M Chipset

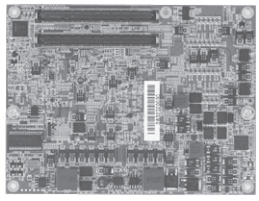


Double deck DDR3 SO-DIMM

DDR3 DualView

Features

- Socket P for Intel® Core™2 Duo processor with FSB 667/800/1066 MHz
- Intel® GM45 + ICH9M chipset
- With high performance integrated graphics controller and discrete solution through PCIe x16 interface
- 21 lanes of PCI Express
- 8 USB 2.0 ports



▲ Rear view

System

CPU	Socket P for Intel® Core™2 Duo processor with FSB 667/800/1066 MHz
System Memory	2 x 204-pin SO-DIMM support DDR3-800/1066 max. up to 8 GB
Chipset	Intel® GM45 + ICH9M
BIOS	AMI
SSD	N/A
Watchdog Timer	255 levels, 1~255 sec.
Expansion Interface	1 x PCIe x16 graphics port supports for SDVO or PCIe x1 devices 5 x PCIe lanes support for 1 x PCIe x4 + 1 x PCIe x1 or 5 x PCIe x1 devices 4 x 32-bit PCI bus masters
Battery	N/A
Power Requirements	Intel® Core™2 Duo T9400 @2.53 GHz, 2GB DDR3 Max. RMS: +5VSB @ 124mA, +12V @ 2.369A
Size	125 x 95 mm
Board Thickness	1.6 mm
Temperature	0° ~ +60°C (32°F ~ 140°F), operation
Relative Humidity	10% ~ 95% relative humidity, non-condensing

I/O

MIO	1 x IDE; PATA-100 1 x LPC interface
SATA	3 x SATA-300
Hardware Monitoring	N/A
Ethernet	1 port as 10/100/1000Mbps supports Wake-on-LAN, RPL/PXE Boot ROM with Intel® 82574L
Audio	HD-Link audio interface to baseboard for external Codec
USB	8 x USB 2.0
SMBus	Yes
I2C	Yes
GPIO	4 Channels IN & 4 Channels OUT
ITP port	ITP7500 standard compliant

Display

Chipset	Intel® GMA 4500HD graphics core
Memory Size	Intel® DVMT 5.0 compliant
Display Interface	1 x VGA 1 x LVDS; 18/24-bit single/dual channel

Packing List

Quick installation guide, user's manual/utility CD

Ordering Information

Standard	
CEM850VG (P/N: E38D850100)	COM Express type 2 module with socket P, VGA/LVDS LCD, 10/100/1000Mbps Ethernet

Optional	
CEB94000	ATX form factor baseboard
5078D850100E	CEM850 heatspreader module for PGA type CPU
5078D830100E	COM Express SoM low profile cooling kit with fan

* All specifications and photos are subject to change without notice.